

## ORGANIZING INFORMATION

### THE CONFERENCE IS HELD AT:

SOŠ a SOU informatiky a spojů  
Čichnova 23, 624 00 BRNO-Komín

### How to get there: by a car (see incl. plan)

From the Brno Trade Fair Exhibition Centre go in direction Brno-dam. After approx. 4km you will see the OPEL car shop centre, on the left side. At the crossroads in front of the OPEL go to the left, at the next crossroads to the right and on the right side you will see an educational centre:

SOŠ A SOU INFORMATIKY A SPOJŮ  
street Čichnova 23, BRNO-Komín

### BINDING APPLICATIONS:

Will be mailed together with obligatory demand for accommodation with meals before **October 14, 2011** to the address:

SMT-INFO consortium  
Údolní 53, 602 00 BRNO  
CZECH REPUBLIC  
e-mail: [smtinfo@nextra.cz](mailto:smtinfo@nextra.cz)  
fax: 00420-546 211 009

### Accommodation with meals:

Participants will be accommodated in the BOBY CENTRUM Brno \*\*\*

### Registration:

In the conference hall

October 18, 2011 8.30 – 8.50 a.m.

### PROFESSIONAL GUARANTOR:

SMT-INFO, Údolní 53, 602 00 Brno  
CZECH REPUBLIC

tel.: 00420-541 146 113  
mobil: 00420-602 542 966  
fax: 00420-546 211 009  
e-mail: [smtinfo@nextra.cz](mailto:smtinfo@nextra.cz)  
Internet: [www.smtinfo.cz](http://www.smtinfo.cz)

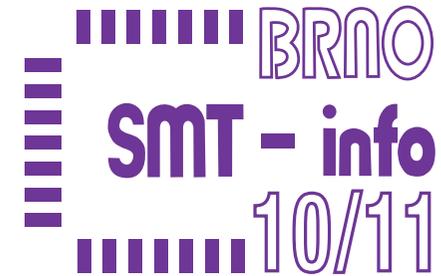
## SMT-INFO CONSORTIUM

in cooperation with

**FEKT VUT Brno  
and**

**SOŠ A SOU INFORMATIKY A SPOJŮ**

have the pleasure to invite you  
to participate in the international conference



**SOLDERING AND CLEANING  
PCB's IN ELECTRONICS**

**NEW TRENDS  
IN MICROELECTRONICS**

October 18, 2011  
SOŠ a SOU informatiky a spojů  
Čichnova 23, Brno-Komín

event code 10/11

SMT-INFO Consortium  
Údolní 53  
602 00 BRNO  
Czech Republic

**CONFERENCE ORIENTATION:**

- SOLDERING AND CLEANING IN ELECTRONICS
- NEW TRENDS IN MICROELECTRONICS
- TECHNIQUES IN REPAIRING

**PROFESSIONAL OFFER**

- Conference participants will be acquainted with the latest information on above mentioned topics presented by specialist from prestigious companies.
- In a room adjacent the lecture theatre, the following company stands will be installed and professional literature and demonstration equipment will be offered there:

<b>AIR PRODUCTS</b>	<b>PAN ELECTRONICS</b>
<b>AMTEST</b>	<b>SMT plus</b>
<b>LASER JOB</b>	<b>SMT SERVICE</b>
<b>LUKON THERMAL SOLUTIONS</b>	

Advertisement tables will be available for the conference participants and visitors, providing propagation of their own products and offer of non-used/used technological equipment and services.

**THEMATIC ORIENTATION OF OTHER EVENTS ORGANIZED BY SMT-INFO:**

**SMT-INFO Seminar 02/12 Brno, February 14, 2012**  
Technical and Business Seminar

- PCB DESIGN SYSTEMS
- COMPLEX PRODUCTION LINES FOR MODERN ASSEMBLY
- INSPECTION SYSTEMS

**PROFESSIONAL GUARANTOR:**

**SMT-INFO consortium, Údolní 53, 602 00 Brno**  
**mobil:** 00420-602 542 966  
**fax:** 00420-546 211 009  
**e-mail:** smtinfo@nexta.cz

**CONFERENCE SCHEDULE**

**Tuesday, October 18, 2011**

- 8.50 - Conference Opening
- 9.00 - Ecology and Trends in the PCB Production in Standards IEC/TC : 91,111 ... /K. Jurák, Praha/
- 9.20 - Low-Silver Soldering Materials for SMT Production /J. Pulchart, SENJU METAL EUROPE Praha/
- 9.40 - Improved Printing Results with Patch Work® Stencils (step stencils) and Nanowork Stencils (Nanocoated Stencils) /A. Axmann, LASER JOB Furstenfeldbruck/
- 10.20 - Coffee, Refreshment
- 10.40 - No Change-Over Time for PCBs of Different Sizes at Curing or Drying Processes /P. Heilmann, LUKON THERMAL SOLUTIONS Tauffelen/
- 11.00 - Back Side Reflow /M. Hurban, REHM THERMAL SYSTEMS Příbor/
- 11.20 - High Flexibility in Selective Soldering Process /J. Elbert, INERTEC Kreuzwertheim T. Kollár, J. Vondráček, AMTEST Brno/
- 12.00 - News about SMT Reflow Soldering and Solution for Thermal Drying and Curing Process /A.Schuster, SMT MASCHINEN Wertheim, M. Galajda, SMT SERVICE Košice/
- 12.40 - Where is Soft Soldering Reached? Latest in Assortment one of the World Wide Producer – Firm ERSA /M. Duda, PBT Rožnov p. Radhoštěm/
- 13.20 - Lunch
- 14.00 - Latest Trends in Water Base Cleaning – Problems and Solutions /V. Sítko, PBT Rožnov p. Radhoštěm/
- 14.20 - Cleaning Chemistry for Flux Residues Removing after LF Soldering /D. Joura, DCT CHEMICALS Černá Hora/
- 14.40 - Practical Experience in Selective Soldering in Firm PANASONIC AVC /P. Gábriš, PANASONIC AVC Plzeň/
- 15.00 - NitroFas – Soldering in Inert Atmosphere /M. Hanák, Z. Mrštný, AIR PRODUCTS CZ/SK/
- 15.20 - Methods of Surface Mounted Assembly for Electronic Modules /J. Šandera, FEKT VUT Brno, SMTPLUS.Cz Brno/
- 15.40 - New OSP Generation for LF Process and Solderability Tests /J. Starý, FEKT VUT Brno, SMTPLUS.Cz Brno/
- 16.00 - Conference Closing, Discussion

**Lectures in English and German will be interpreted.  
Program changes reserved.**

**Obligatory application for international conference**

**SOLDERING AND CLEANING PCB's  
IN ELECTRONICS**

**NEW TRENDS IN MICROELECTRONICS**

**October 18, 2011**

Name and surname, title .....

Factory name and address (ZIP code) .....

Job function .....

Telephone ..... Telefax .....

e-mail .....

**1. Accommodation**

from 17 to 18 October, 2011 **yes-no**

**2. Lunch**

October 18, 2011 **yes-no**

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Participant signature	Stamp and signature of the organization